



DMN2400UV

DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected up to 2kV
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 standards for High Reliability

Mechanical Data

- Case: SOT-563
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Weight: 0.006 grams (approximate)

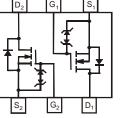
ESD PROTECTED TO 2kV



SOT-563



Bottom View



Top View Internal Schematic

Ordering Information (Note 3)

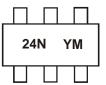
Part Number	Case	Packaging
DMN2400UV-7	SOT-563	3,000/Tape & Reel
DMN2400UV-13	SOT-563	10,000/Tape & Reel

Notes: 1. No purposefully added lead.

2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.

3. For packaging details, go to our website at http://www.diodes.com.

Marking Information



24N = Marking CodeYM = Date Code Marking Y = Year (ex: W = 2009) M = Month (ex: 9 = September)

Date Code Key

Date Code Key												
Year	200	9	2010		2011	20	12	2013		2014	2	2015
Code	W		Х		Y	2	Ζ	А		В		С
Month	Jan	Feb	Mar	Apr	Mav	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteris		Symbol	Value	Units	
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±12	V
Continuous Drain Current (Note 4)	ent (Note 4) $\begin{array}{c} Steady \\ State \\ T_A = 25^{\circ}C \\ T_A = 85^{\circ}C \end{array}$		ID	1.33 0.84	A
Pulsed Drain Current			IDM	3	А

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 4)	Po	530	mW
	FD		
Thermal Resistance, Junction to Ambient	R _θ JA	233.8	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

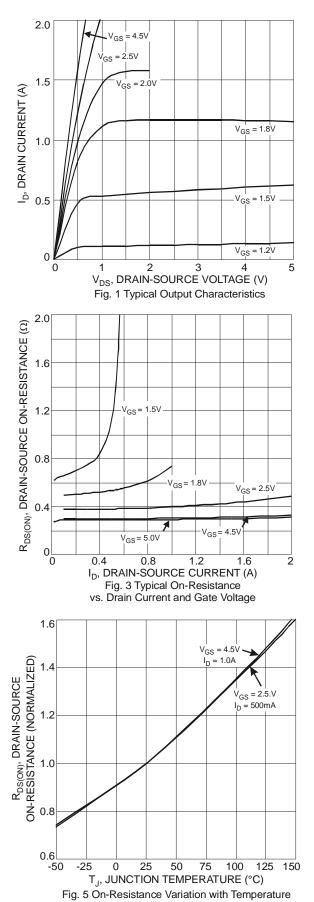
Electrical Characteristics @T_A = 25°C unless otherwise specified

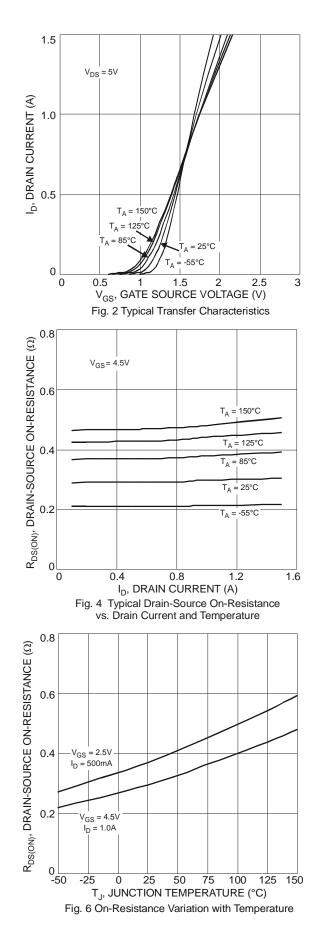
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current TJ = 25°C	IDSS	-	-	100	nA	$V_{DS} = 20V, V_{GS} = 0V$
Cata Sauraa Laakaga		-	-	±1.0	μA	$V_{GS} = \pm 4.5 V, V_{DS} = 0 V$
Gate-Source Leakage	I _{GSS}	-	-	±50		$V_{GS} = \pm 10V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	0.5	-	0.9	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$
		-	0.3	0.48		$V_{GS} = 5.0V, I_D = 200mA$
		-	0.35	0.5		$V_{GS} = 4.5V, I_D = 600mA$
Static Drain-Source On-Resistance	R _{DS (ON)}	-	0.45	0.7	Ω	$V_{GS} = 2.5V, I_D = 500mA$
		-	0.55	0.9		V _{GS} = 1.8V, I _D = 350mA
		-	0.65	1.5		$V_{GS} = 1.5V, I_D = 50mA$
Forward Transfer Admittance	Y _{fs}	-	1.4	-	S	$V_{DS} = 10V, I_D = 400mA$
Diode Forward Voltage (Note 5)	V _{SD}		0.7	1.2	V	$V_{GS} = 0V, I_S = 150mA,$ f = 1.0MHz
DYNAMIC CHARACTERISTICS (Note 6)						
Input Capacitance	Ciss	-	36.0	-	pF	
Output Capacitance	C _{oss}	-	5.7	-	pF	V _{DS} =16V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	-	4.2	-	pF	1 = 1.0MH2
Gate Resistance	Rg	-	68	-	Ω	$V_{DS} = 0V, V_{GS} = 0V,$
Total Gate Charge	Qg	-	0.5	-	nC	V _{GS} =4.5V, V _{DS} = 10V,
Gate-Source Charge	Q _{gs}	-	0.07	-	nC	I _D =250mA
Gate-Drain Charge	Q _{gd}	-	0.1	-	nC	7
Turn-On Delay Time	t _{D(on)}	-	4.06	-	ns	
Turn-On Rise Time	tr	-	7.28	-	ns	$V_{DD} = 10V, V_{GS} = 4.5V,$
Turn-Off Delay Time	t _{D(off)}	-	13.74	-	ns	$R_{L} = 47\Omega, R_{G} = 10\Omega,$ $I_{D} = 200 \text{mA}$
Turn-Off Fall Time	t _f	-	10.54	-	ns	D = 20011A

4. Device soldered onto FR-4 PCB, minimum recommended soldering pad dimensions (25.4mm x 25.4mm x1.6mm, 2oz Cu pad: 0.18mm² x 6). Notes: Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to product testing.

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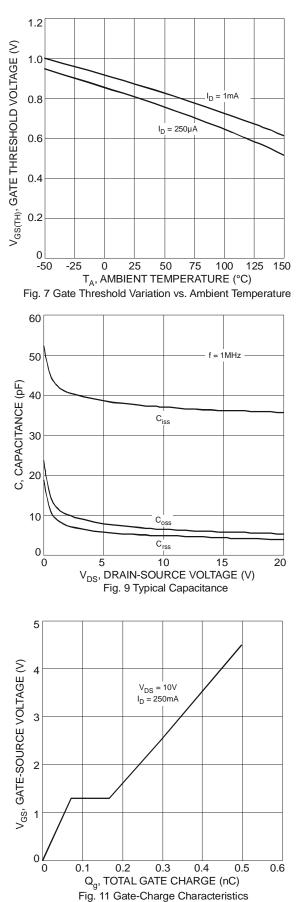


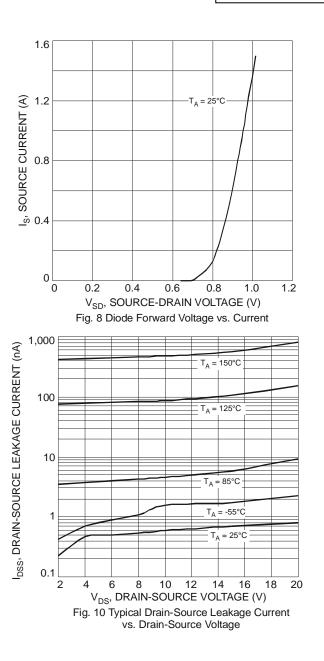




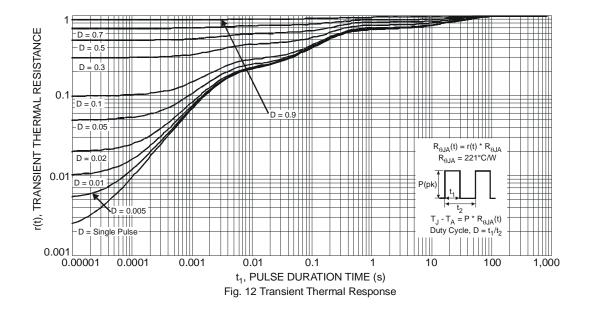
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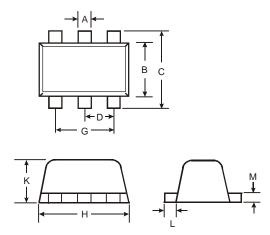






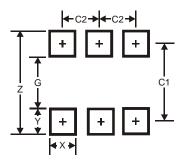


Package Outline Dimensions



	SOT-563							
Dim	Min	Max	Тур					
Α	0.15	0.30	0.20					
В	1.10	1.25	1.20					
С	1.55	1.70	1.60					
D	-	-	0.50					
G	0.90	1.10	1.00					
н	1.50	1.70	1.60					
Κ	K 0.55 0.60 0.60							
L	0.10	0.30	0.20					
Μ	0.10	0.18	0.11					
All	All Dimensions in mm							

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5



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